



HexFlow® RTM6/RTM6-2

180°C Epoxy System for Resin Transfer Molding
and Infusion Technologies



Product Data Sheet

Description

HexFlow® RTM6 is a mono-component aerospace qualified resin system specially developed for Liquid Composite Molding technologies, such as LRI and RTM.

HexFlow® RTM6-2 is the bi-component version of HexFlow® RTM6. It is delivered as two different components providing several benefits over HexFlow® RTM6: air shipment is allowed, storage at $23 \pm 5^\circ\text{C}$ for 12 months and bigger packages are possible (up to 378 kg).

HexFlow® RTM6-2 is chemically the same as HexFlow® RTM6 and has the same high performances after mixing of Part A and Part B. Their mixing ratio by weight is Part A : Part B (100:68,1).

After mixing of Part A and Part B, service temperatures from -60°C up to 120°C and cycle processing flexibility make HexFlow® RTM6 ideal for primary & secondary aerospace structures. Long injection windows due to HexFlow® RTM6 low viscosities are easily reached facilitating large parts manufacturing.

HexFlow® RTM6 resin can be used with a wide range of HexForce®, HiTape® and HiMax® reinforcements. If needed, binders and veils are also available and fully compatible with HexFlow® RTM6. They provide easy preforming properties, reinforcement dimensional stability and toughening properties.

HexFlow® RTM6 when combined with HiTape® & HiMax® has comparable mechanical properties to latest generation preregs.

Advantages

Before Mixing

- Longer out life storage of Part A & Part B: 12 months at room temperature ($23 \pm 5^\circ\text{C}$)
- Easier transportation regulations: aircraft shipment is allowed

After Mixing

- Qualified and well-known for vacuum infusion and RTM process
- High glass transition temperatures: dry¹: $T_g > 200^\circ\text{C}$; wet²: $T_g > 160^\circ\text{C}$
- Low moisture absorption: 2,0 – 3,0%
- $< 100\text{mPa.s}$ at process temperatures
- Mechanical properties similar to latest generation preregs when combined with HiTape® & HiMax® reinforcements
- Flexible processing and cure cycles

⁽¹⁾ Dry: 24h at 105°C

⁽²⁾ Wet: 14 days in water at 70°C



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HexFlow[®] RTM6 Uncured Resin Properties (HexFlow[®] RTM6-2 After Mix)

Viscosity

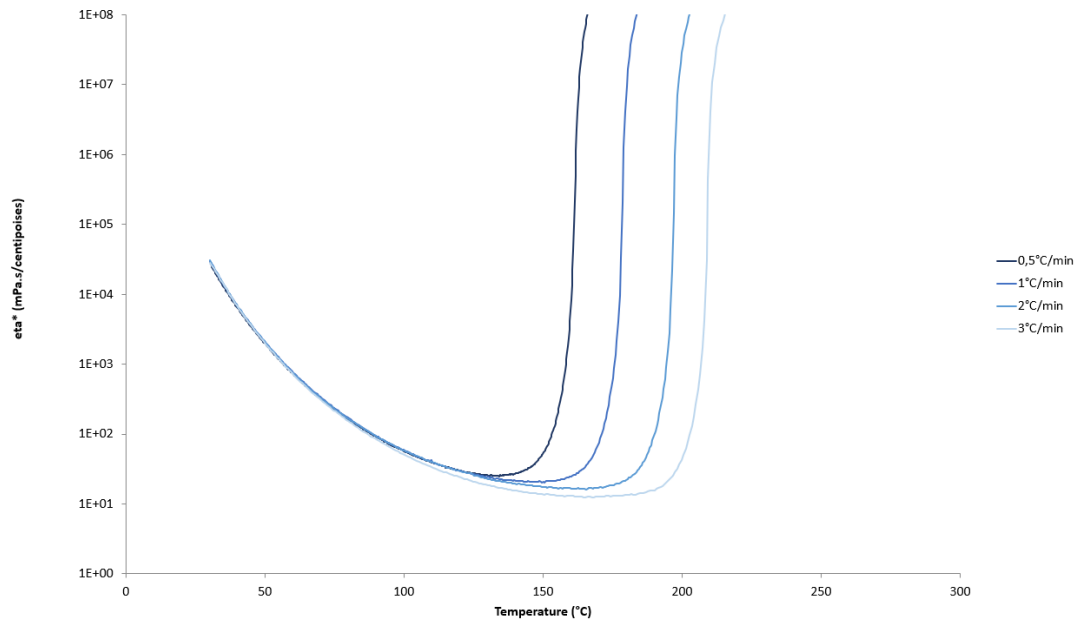


Figure 1: Rheology Profile of HexFlow[®] RTM6

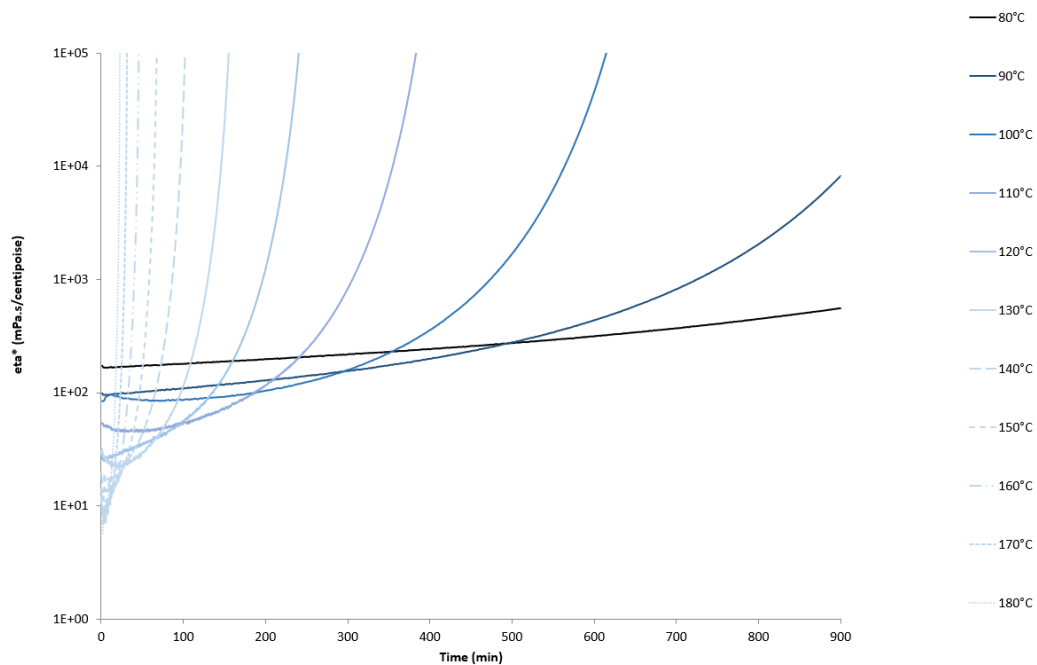


Figure 2: Isothermal Viscosities of HexFlow[®] RTM6



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Gel Point

| Temperature (°C) | Gel Time: G' & G'' Crossover (h:min) | Time to Reach 1000 mPa's (h:min) | Time to Reach 200 mPa's (h:min) |
|------------------|---|-------------------------------------|------------------------------------|
| 80 | > 15:00 | > 15:00 | Viscosity > 200 mPa's |
| 90 | > 15:00 | 12:00 | |
| 100 | 11:30 | 8:00 | 5:30 |
| 110 | 7:30 | 5:00 | 4:00 |
| 120 | 4:00 | 3:00 | 2:30 |
| 130 | 2:40 | 2:00 | 1:40 |
| 140 | 1:40 | 1:20 | 1:10 |
| 150 | 1:00 | 0:55 | 0:50 |
| 160 | 0:45 | 0:40 | 0:35 |
| 170 | 0:30 | 0:25 | 0:25 |
| 180 | 0:20 | 0:20 | 0:15 |

Thermokinetics

| Standard DSC Parameters | | | |
|-------------------------|----------------|-------------|--------------|
| Tg Midpoint (°C) | Enthalpy (J/g) | T Peak (°C) | T Onset (°C) |
| -15 | 450 | 240 | 215 |

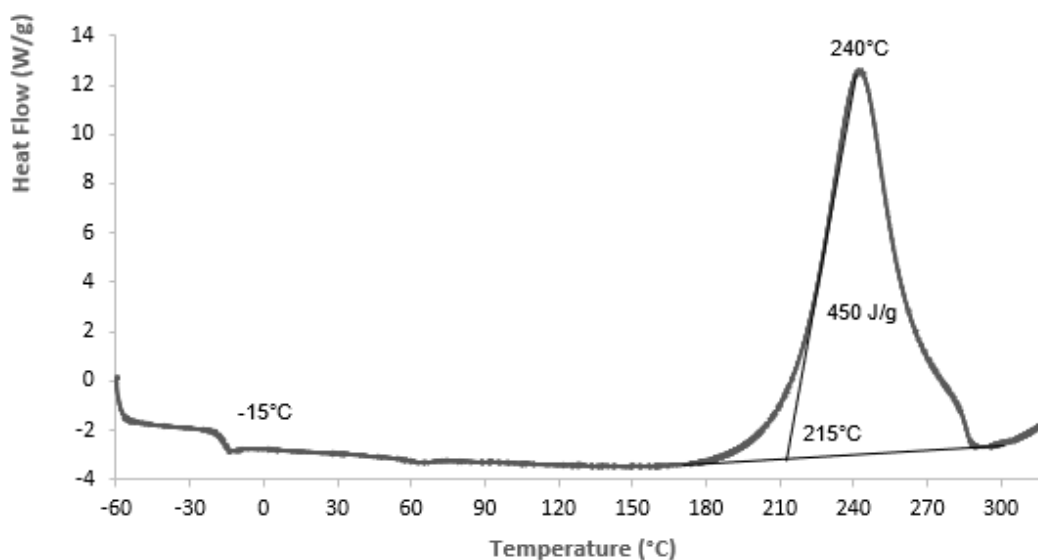


Figure 3: Standard DSC of HexFlow[®] RTM6



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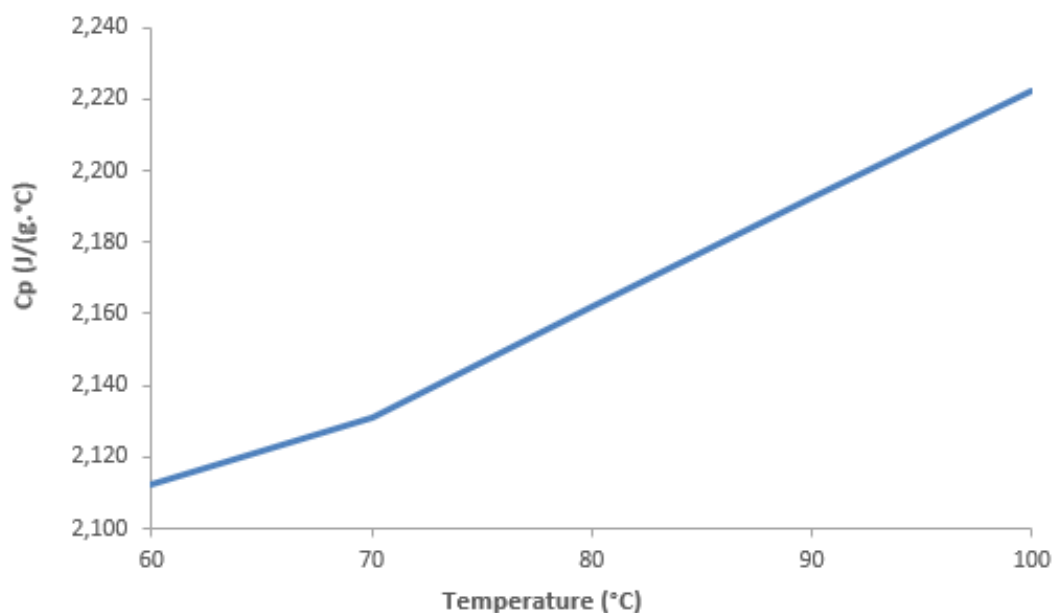


Figure 4: Specific Heat of HexFlow[®] RTM6

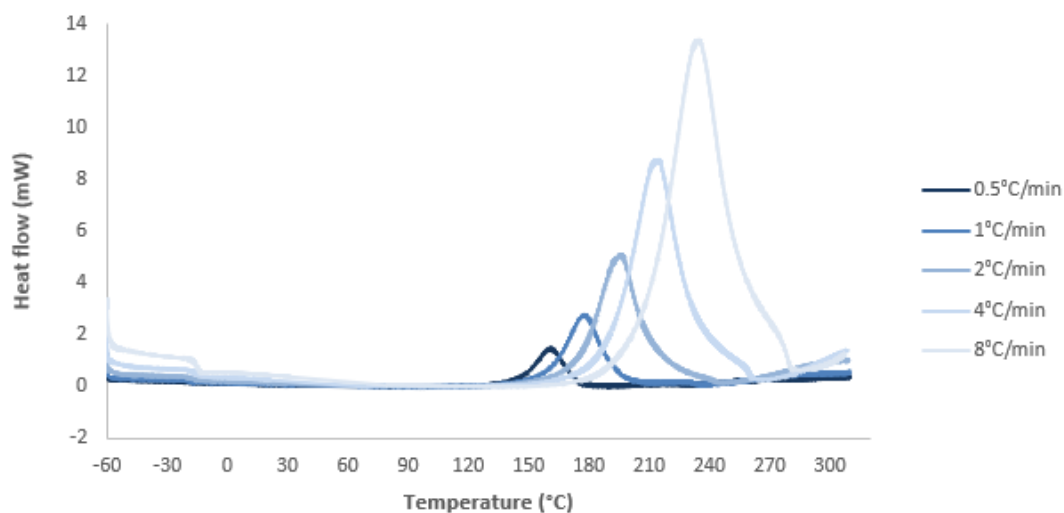


Figure 5: Standard DSC at Various Heating Rates of HexFlow[®] RTM6



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Processing Recommendations

For uncured resin handling, please refer to "[Hexcel HexFlow[®] RTM6/RTM6-2 Safety Processing Guidelines](#)" document.

Defrosting

- 24h at 23°C ± 5°C (10kg)

Process Parameters (Infusion or RTM)

- Preheat resin at 80°C (please refer to "[Hexcel HexFlow[®] RTM6/RTM6-2 Safety Processing Guidelines](#)" document for maximum preheating time)
- Mold temperature: between 120°C and 180°C, at constant temperature
- Injection / infusion lines: 90-110°C
- Mold / bagging leakage: below 15 mbar in 5 min
- Vacuum Infusion: below 5 mbar
- RTM Piston Pressure: atm to 5 bars

Cure Cycle

- 90 min minimum at 180°C - no post cure required (degree of cure: $\alpha > 90\%$)

For additional technical information on processing & curing, please contact **Hexcel Technical Support**.



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Cured Resin Mechanical Properties

Neat resin cure cycle (convention oven accurate to +/- 3°C)

⁽¹⁾ Dry: 24h at 105°C

⁽²⁾ Wet: 14 days in water at 70°C

| Parameter (Unit) | Value | | |
|--|---------------|---------------|----------------|
| K1c (MPa.m ^{1/2}) | 0,6 | | |
| Density (g/cm ³) | 1,14 | | |
| Coefficient of thermal expansion (10 ⁻⁶ K ⁻¹) | -50°C to 20°C | 20°C to 100°C | 100°C to 180°C |
| | 55 | 65 | 80 |
| Moisture uptake (%) | 2,0 – 3,0 | | |

Compression (ASTM D695)

| Conditioning | Dry ¹ | | Wet ² | |
|-------------------------|------------------|-------|------------------|-------|
| Test Temperature | 23°C | 120°C | 23°C | 120°C |
| Yield strength (MPa) | 140 | 85 | 130 | 65 |
| Yield strength (ksi) | 20,3 | 12,3 | 18,8 | 9,4 |
| Ultimate strength (MPa) | 325 | 190 | 320 | 175 |
| Ultimate strength (ksi) | 47,2 | 27,3 | 46,8 | 25,3 |
| Modulus (GPa) | 3,4 | 2,8 | 3,4 | 2,4 |
| Modulus (msi) | 0,50 | 0,40 | 0,49 | 0,36 |

Tensile (ASTM D638)

| Conditioning | Dry ¹ | | Wet ² | |
|-------------------------|------------------|-------|------------------|-------|
| Test Temperature | 23°C | 120°C | 23°C | 120°C |
| Ultimate strength (MPa) | 95 | 70 | 80 | 40 |
| Ultimate strength (ksi) | 13,9 | 9,8 | 11,9 | 5,3 |
| Modulus (GPa) | 3,1 | 2,5 | 3,0 | 1,9 |
| Modulus (msi) | 0,45 | 0,36 | 0,44 | 0,27 |

DMA (EN6032)

| Tg (°C) | Dry ¹ | Wet ² |
|--------------|------------------|------------------|
| Onset | 210 | 175 |
| Loss Modulus | 215 | 190 |
| Tanδ | 230 | 225 |



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Laminate Mechanical Properties

Reinforcement: HexForce® G0926 HS-6K, 375g/m² 5H Satin (WITHOUT BINDER).

⁽³⁾ Dry: 23 ± 5°C / 50 ± 7% RH

⁽⁴⁾ Wet: 70 ± 5°C / 85 ± 7% RH until saturation

Compression (EN2850A1)

| Test | Lay up | Property | Dry ³ | | Wet ⁴ | |
|-----------------|------------------|-------------------------|------------------|-----------|------------------|-----------|
| | | | 23 ± 5°C | 120 ± 5°C | 23 ± 5°C | 120 ± 5°C |
| Compression 0° | [0] ₆ | Ultimate strength (MPa) | 730 | 570 | 555 | 440 |
| | | Ultimate strength (ksi) | 105,9 | 82,7 | 80,5 | 63,1 |
| | | Modulus (GPa) | 60,9 | 63,9 | 64,1 | 64,9 |
| | | Modulus (msi) | 8,83 | 9,27 | 9,30 | 9,41 |
| Compression 90° | | Ultimate strength (MPa) | 660 | 545 | 545 | 415 |
| | | Ultimate strength (ksi) | 95,7 | 79,0 | 79,0 | 60,2 |
| | | Modulus (GPa) | 62,6 | 62,2 | 62,8 | 71,7 |
| | | Modulus (msi) | 9,08 | 9,02 | 9,11 | 10,36 |

In plane shear IPS (EN6031)

| Lay up | Property | Dry ³ | | Wet ⁴ | | | |
|-----------------------------------|-------------------------|------------------|-----------|------------------|----------|----------|-----------|
| | | 23 ± 5°C | 120 ± 5°C | 23 ± 5°C | 70 ± 5°C | 90 ± 5°C | 120 ± 5°C |
| [+45/-45] _{2S} (8 plies) | Ultimate strength (MPa) | 115 | 85 | 95 | 95 | 85 | 70 |
| | Ultimate strength (ksi) | 16,7 | 12,3 | 13,8 | 13,8 | 12,3 | 10,1 |
| | Modulus (GPa) | 3,8 | 3,4 | 4,1 | 4,0 | 3,5 | 2,9 |
| | Modulus (msi) | 0,55 | 0,49 | 0,59 | 0,58 | 0,51 | 0,42 |

Compression after impact CAI (ASTM D7136/ D7137)

| Testing | Lay up | 23 ± 5°C, Dry ³ | | | | | |
|------------|----------------------------------|----------------------------|--------------------|--------------|-------|----------------|-------|
| | | Delaminated area | | Indent depth | | Gross strength | |
| | | (mm ²) | (in ²) | (mm) | (in) | (MPa) | (ksi) |
| 15J impact | [+45/0] _{3S} (12 plies) | 505 | 0,78 | 0,15 | 0,006 | 245 | 35,5 |
| 30J impact | [+45/0] _{3S} (12 plies) | 970 | 1,50 | 0,5 | 0,020 | 215 | 31,2 |



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HexFlow[®] RTM6-2 Part A & B Properties

Viscosity

Part A

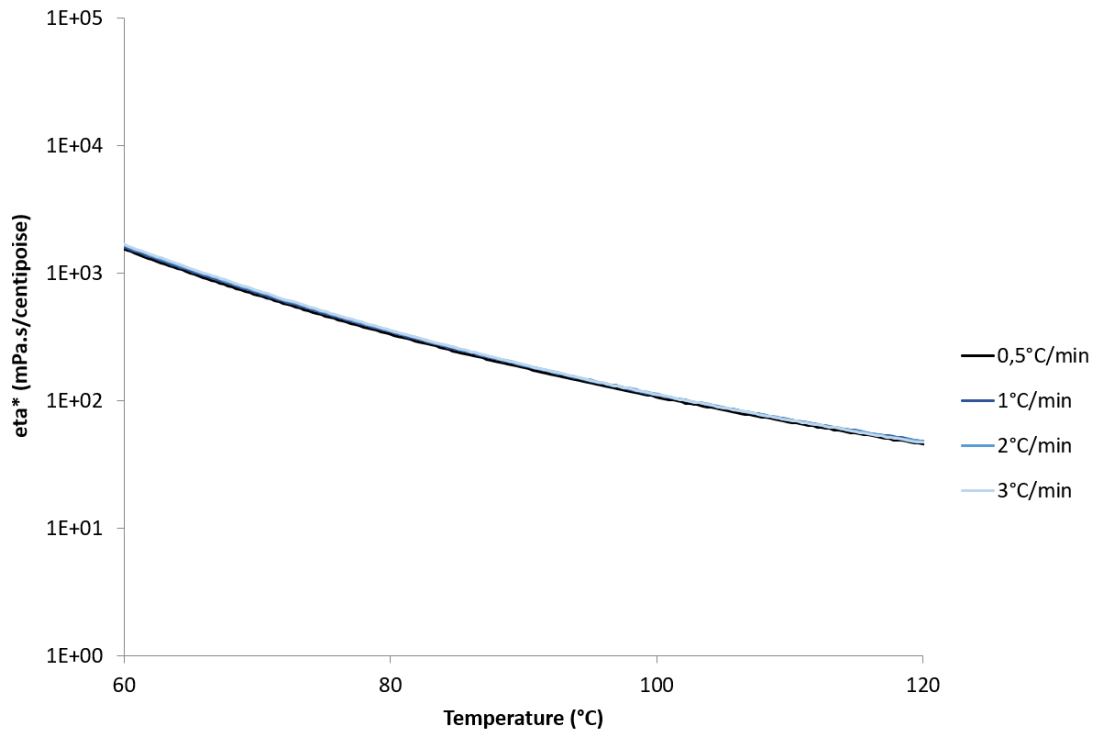


Figure 6: Rheology Profile of HexFlow[®] RTM6-2 Part A

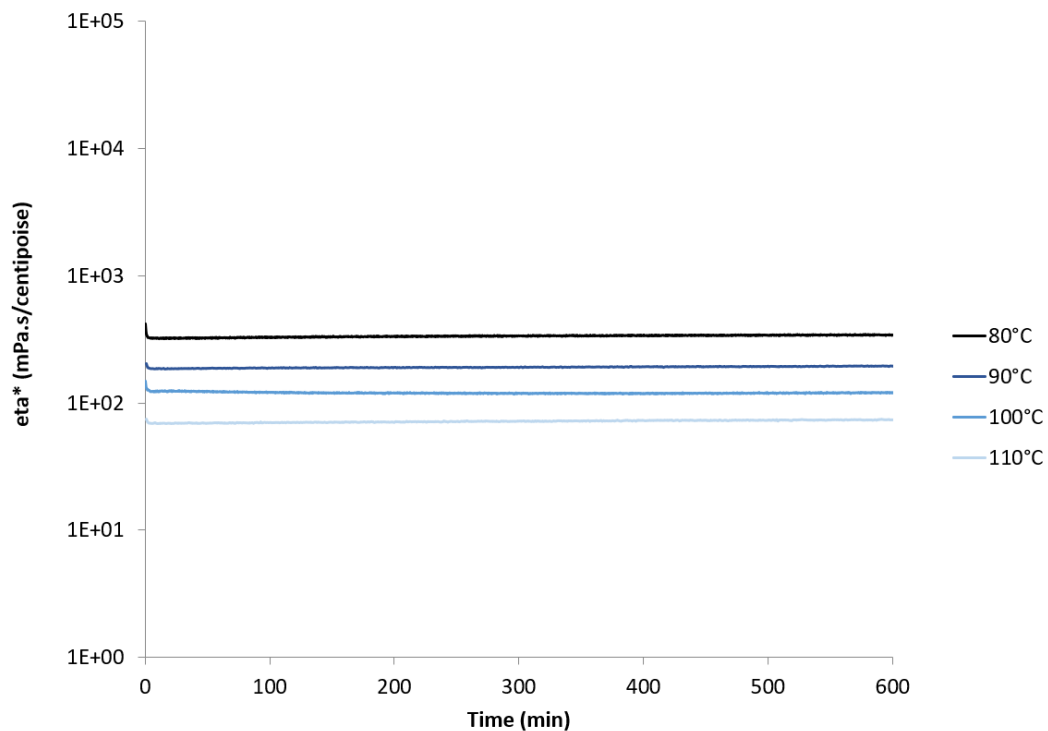


Figure 7: Isothermal Viscosities of HexFlow[®] RTM6-2 Part A



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HexFlow[®] RTM6-2 Part A & B Properties

Viscosity

Part B

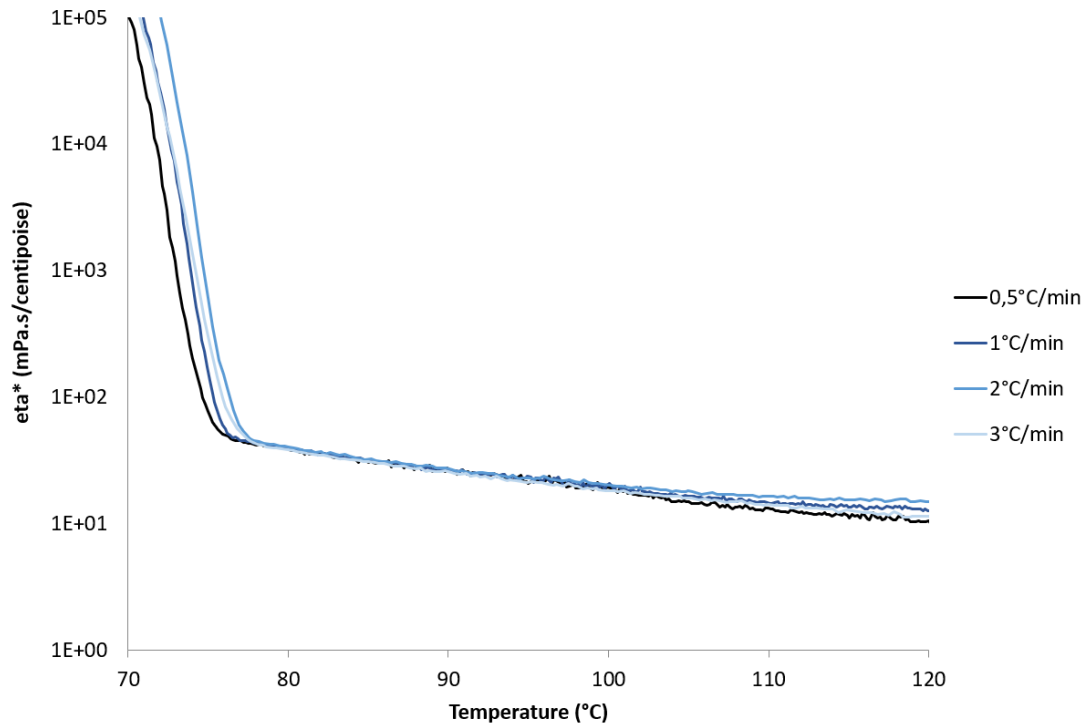


Figure 8: Rheology Profile of HexFlow[®] RTM6-2 Part B

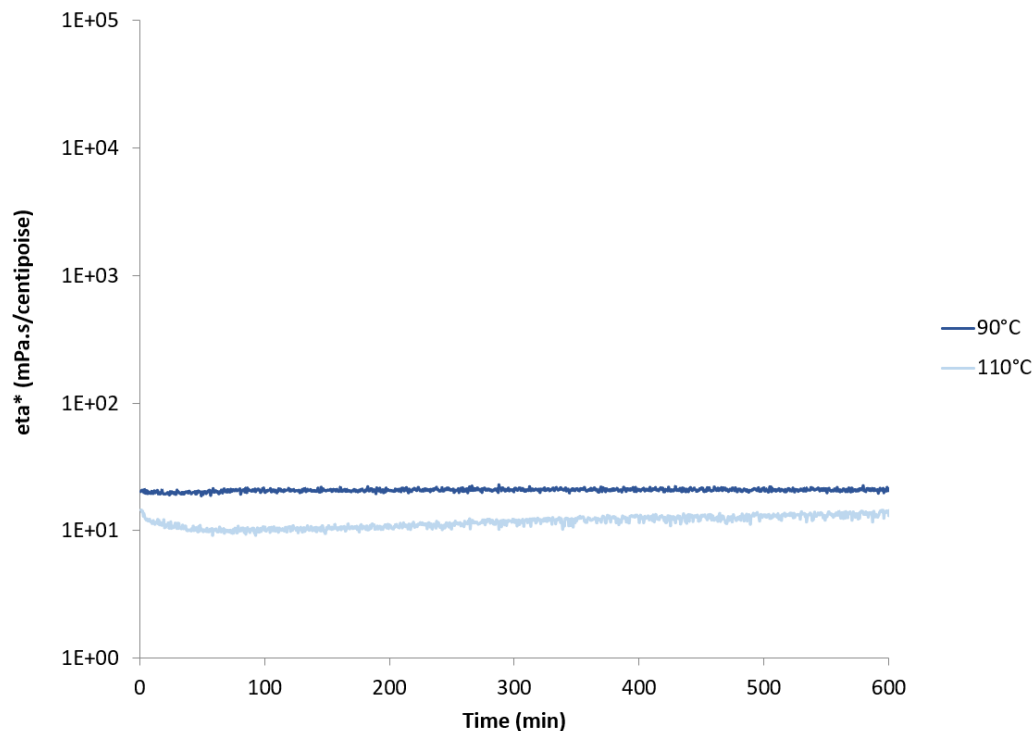


Figure 9: Isothermal Viscosities of HexFlow[®] RTM6-2 Part B



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Thermokinetics Part A

| | Standard DSC Parameters | | | |
|--------|-------------------------|----------------|-------------|--------------|
| | Tg midpoint (°C) | Enthalpy (J/g) | T peak (°C) | T onset (°C) |
| Part A | -20 | 1120 | 330 | 310 |

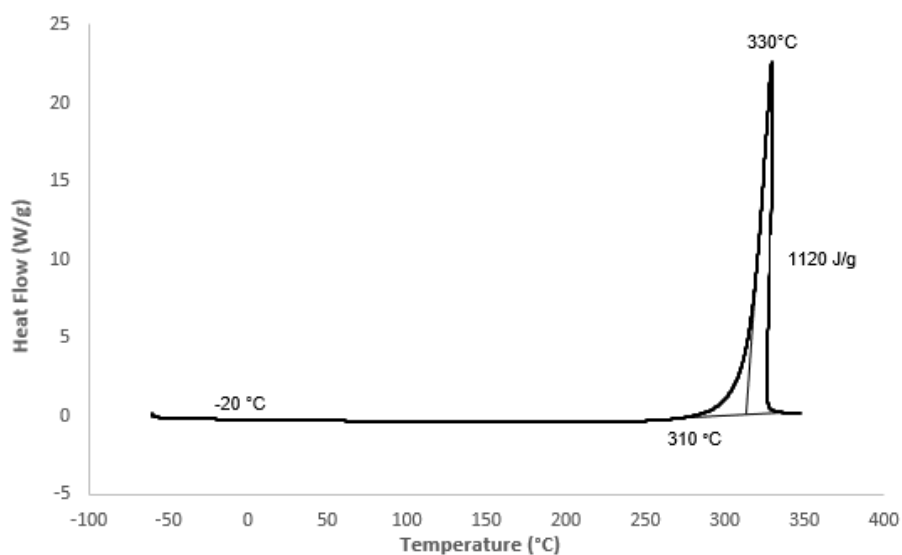


Figure 10: Standard DSC of HexFlow[®] RTM6-2 Part A

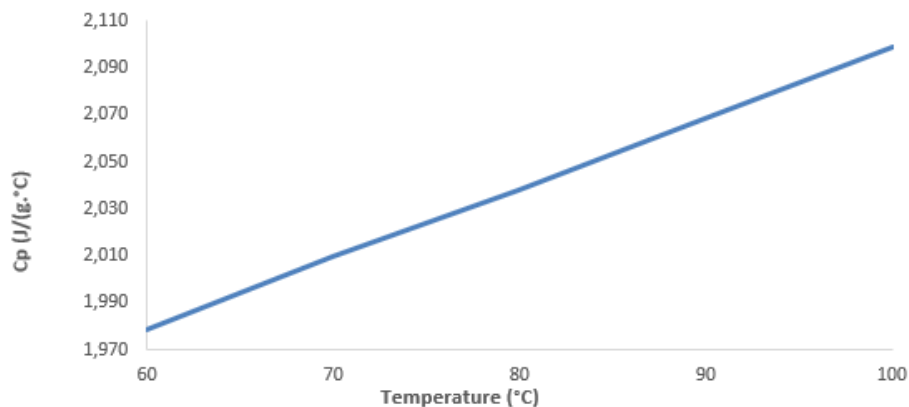


Figure 11: Specific Heat of HexFlow[®] RTM6-2 Part A



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Thermokinetics Part B

| | Standard DSC Parameters | | | | | |
|--------|-------------------------|---------------|---------------|-------------------|----------------------|--------------------|
| | Enthalpy (J/g) | T peak 1 (°C) | T peak 2 (°C) | Softening Tg (°C) | Melting start T (°C) | Melting end T (°C) |
| Part B | 70 | 55 | 75 | 40 | 50 | 80 |

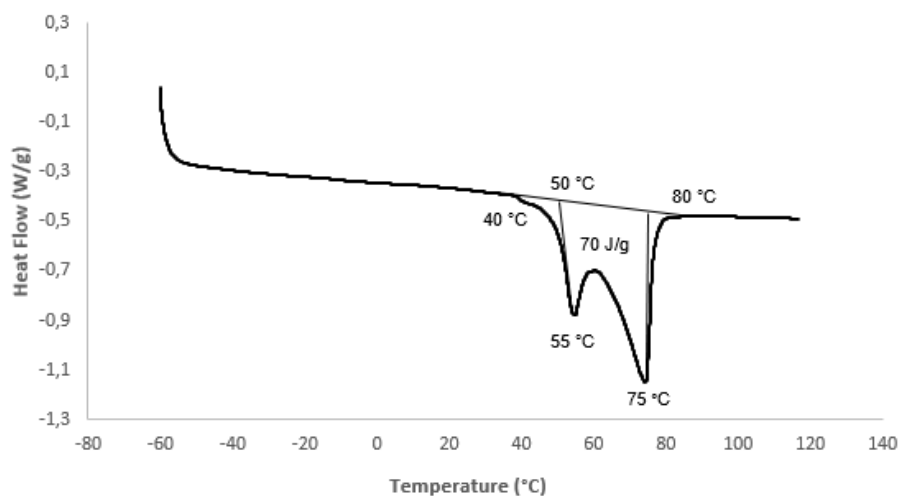


Figure 12: Standard DSC of HexFlow[®] RTM6-2 Part B

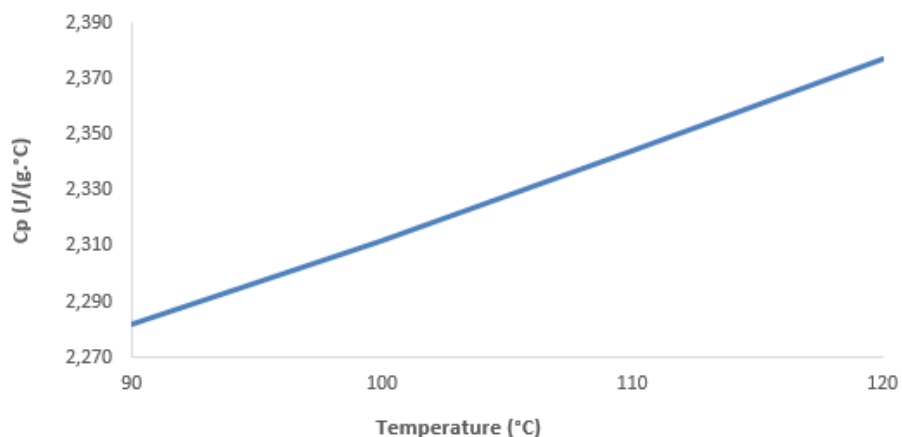


Figure 13: Specific Heat of HexFlow[®] RTM6-2 Part B



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Processing Recommendations

For uncured resin handling, please refer to "[Hexcel HexFlow[®] RTM6/RTM6-2 Safety Processing Guidelines](#)" document.

Defrosting

- Part A & Part B: 24h at 23°C ± 5°C

Mixing

- Pre-heating temperature: Part A ≤ 90°C & Part B 90°C - 110°C
- Mixing ratio by weight: Part A 100: Part B 68,1

*For additional technical information on processing & curing, please contact **Hexcel Technical Support**.*



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Testing Conditions

Uncured Resin Data

Isothermal Viscosities: EN6043

Gap: 0,5mm

Shear rate: 10 rad/s

Strain: 4%

Rheology Profile: EN6043

Gap: 0,5mm

Shear rate: 10 rad/s

Strain: 4%

Temperature range: from 30°C to 250°C

Standard DSC: EN6041

Heating rate: 10°C/min

Temperature range: from -60°C to 350°C

Modulated DSC:

from -50°C to 235°C at 2°C/min

Oscillation: +/-1°C

Period: 120s

Cured Resin Data

K1c: ASTM D5045**Density:** ISO1183**DMA:** EN6032

Mode: fixed frequency, simple cantilever

Amplitude: 15µm

Frequency: 1Hz

Heating rate: 3°C/min

Temperature range: 30°C to 250°C

Compression: ASTM D695

Modulus strain range: 0.1% - 0.5% & 0.3% - 0.5%

Tensile: ASTM D638

Laminate Mechanical Data

Compression: EN2850A1**CAI:** ASTM D7136/ D7137**DMA:** EN6032

Mode: fixed frequency, simple cantilever

Amplitude: 15µm

Frequency: 1Hz

Heating rate: 3°C/min

Temperature range: from 30°C to 250°C

Tensile: EN2561B**IPS:** EN6031



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Transport and Storage of Uncured Resin

Product classification & transport conditions: Please refer to "[HexFlow® RTM6/RTM6-2 Safety Data Sheet](#)."

Shelf Life

- Before mixing (Part A & Part B)
 - 12 months at $23 \pm 5^{\circ}\text{C}$
- After mixing
 - 15 days maximum at $23 \pm 5^{\circ}\text{C}$
 - 9 months at temperatures below -18°C

For more information

Hexcel is a leading worldwide supplier of composite materials to aerospace and industrial markets. Our comprehensive range includes:

- | | | |
|------------------------------------|------------------------------|------------------------|
| ● HexTow® carbon fibers | ● HiFlow® RTM resins | ● Engineered core |
| ● HexForce® reinforcements | ● HexBond® adhesives | ● Engineered products |
| ● HiMax® multiaxial reinforcements | ● HexTool® tooling materials | ● Polyspeed® laminates |
| ● HexPly® prepregs | ● HexWeb® honeycomb | ● & pultruded profiles |
| ● HexAM® additive manufacturing | ● Acousti-Cap® sound | |
| ● HexMC® molding compounds | attenuating honeycomb | |

For U.S. quotes, orders and product information call toll-free 1-800-688-7734. For other worldwide sales office telephone numbers and a full address list, please go to:

<https://www.hexcel.com/contact>

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